规格书编号

SPEC NO :

产品规格书
SPECIFICATION

CUSTOMER 客 户：

PRODUCT 产 品：SAW FILTER

MODEL NO 型 号：HDF820AN SMD-6

MARKING 印 字：HDF6826

PREPARED 编 制：CHECKED 审 核：

APPROVED 批 准：D A T E 日 期：2010-6-23

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司

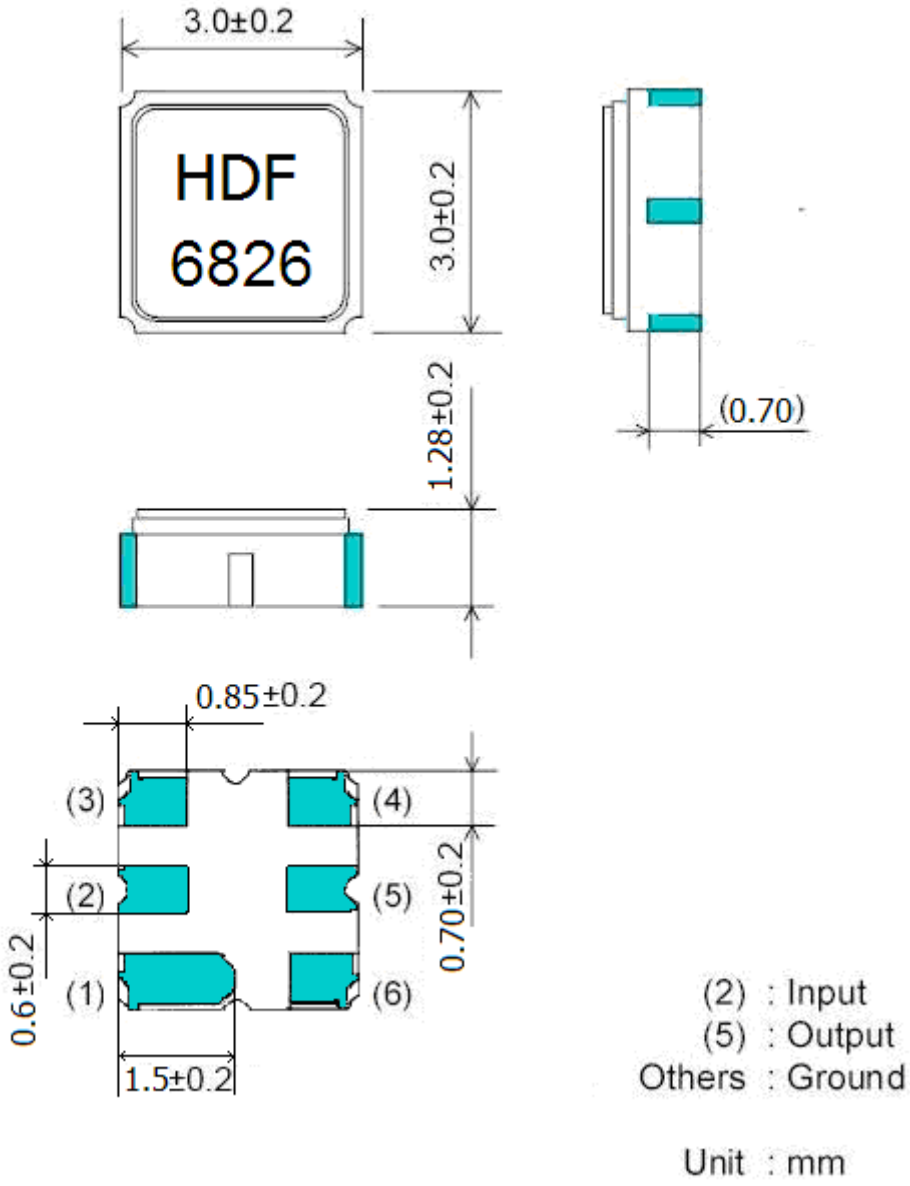
Shoulder Electronics Limited

更改历史记录
History Record

更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark

1. Package Dimension

Unit:mm



2. Marking: HDF6826

HD: Brand
F : Filter
6 : SMD-6
826 : No.

3.Performance

3.1Application

Low-Loss SAW Filter of cordless system.

Center Frequency:820.5 MHz

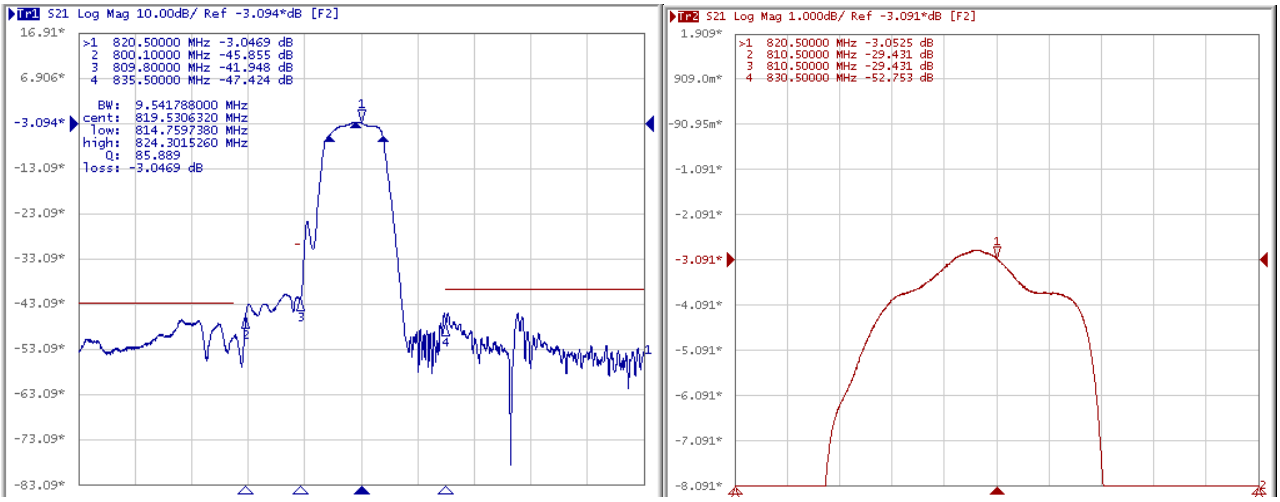
3.2Maximum Rating

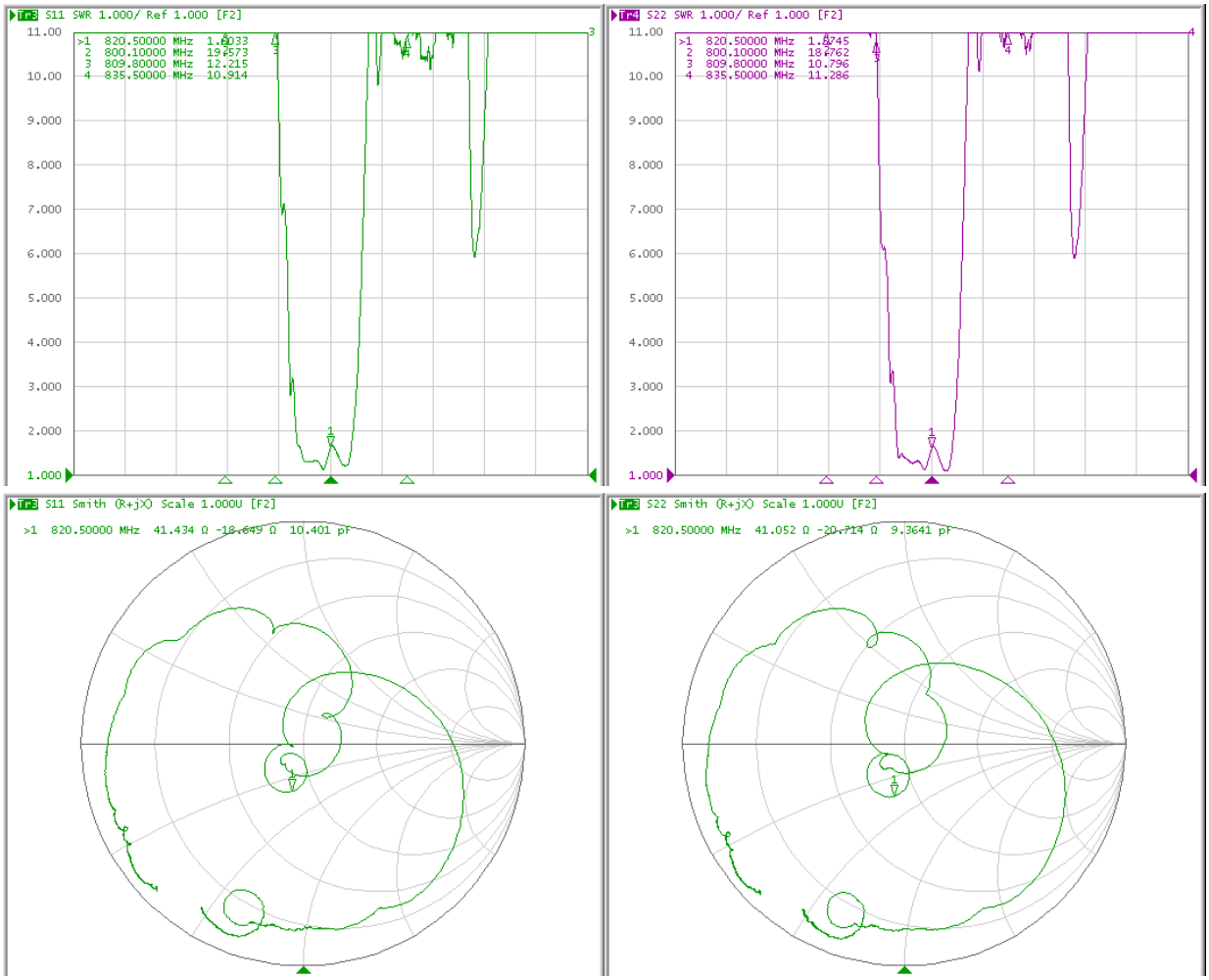
Operation Temperature Range	-40℃ to +85℃
Storage Temperature Range	-40℃to +85℃
DC. Permissive Voltage	0 V DC. max.
Maximum Input Power	11dBm

3.3 Electronic Characteristics

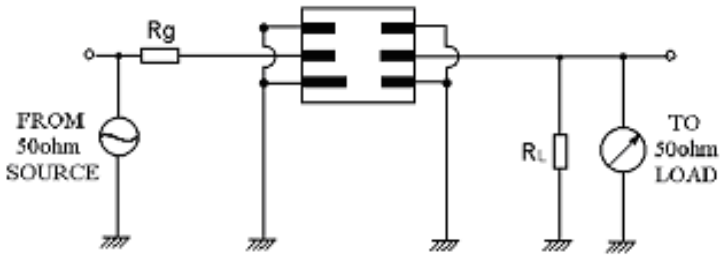
	Unit	Minimum	Typical	Maximum
Center Frequency	MHz	-	820.5	-
Insertion Loss (In Fc +/- 1.5 MHz)	dB	-	3.0	4.5
Pass Band Width	MHz	-	9.5	10.5
Stop Band Rejection 798.1~800.1MHZ 808.8~809.8 MHZ 835.5~871.5 MHZ 880.5~1500MHz	dB	 43 30 40 40	 45 38 42 52	-
Input/Output Impedance	Ohms		50	

3.4 Frequency Characteristics





3.4 Test Circuit



4. ENVIRONMENTAL CHARACTERISTICS

4-1 Temperature cycling

Subject the device to a low temperature of -45℃ for 30 minutes. Following by a high temperature of +25℃ for 5 Minutes and a higher temperature of +85℃ for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in 3.3.

4-2 Resistance to solder heat

Submerge the device terminals into the solder bath at 260℃±5℃ for 10±1 sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications

in 3.3.

4-3 Solderability

Submerge the device terminals into the solder bath at 245℃ ±5℃ for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 3.3.

4-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in 3.3.

4-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in 3.3.

5. REMARK

5.1 Static voltage

Static voltage between signal load & ground may cause deterioration &destruction of the component. Please avoid static voltage.

5.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

5.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.

6. Packing

6.1 Dimensions

(1) Carrier Tape: Figure 1

(2) Reel: Figure 2

(3) The product shall be packed properly not to be damaged during transportation and storage.

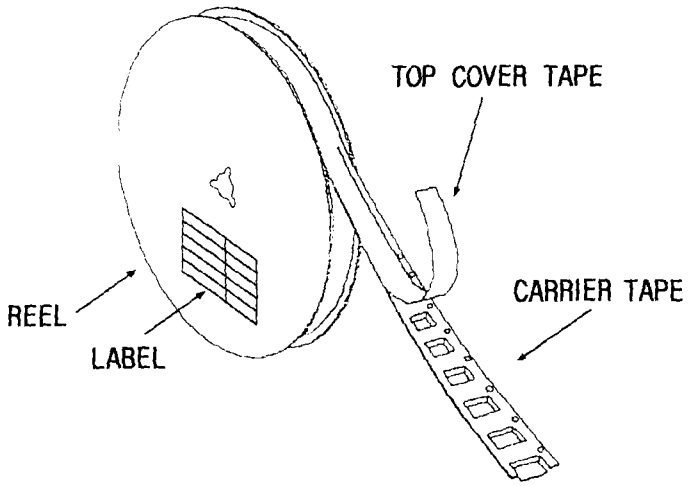
6.2 Reeling Quantity

1000 pcs/reel 7’’

3000 pcs/reel 13’’

6.3 Taping Structure

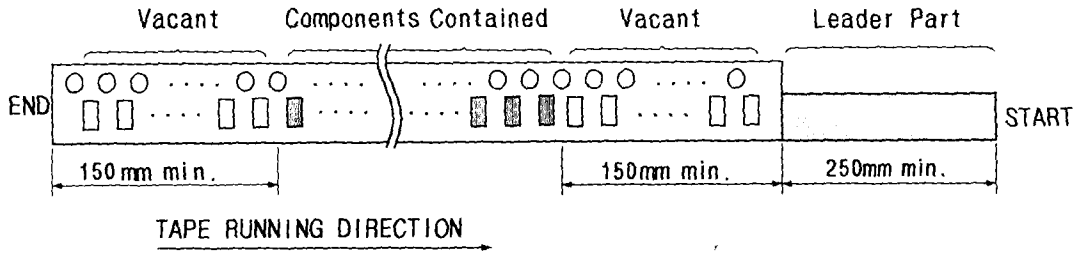
(1) The tape shall be wound around the reel in the direction shown below.



(2) Label

Device Name	
User Product Name	
Quantity	
Lot No.	

(3) Leader part and vacant position specifications.

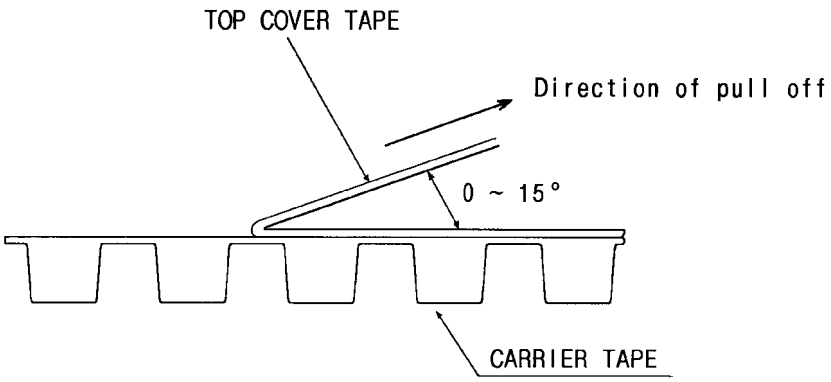


7. TAPE SPECIFICATIONS

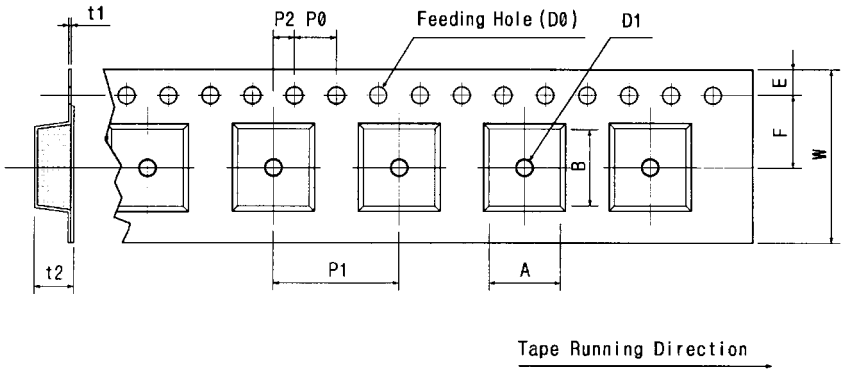
7.1 Tensile Strength of Carrier Tape: 4.4N/mm width

7.2 Top Cover Tape Adhesion (See the below figure)

(1) pull off angle: 0~15°
(2) speed: 300mm/min.
(3) force: 20~70g



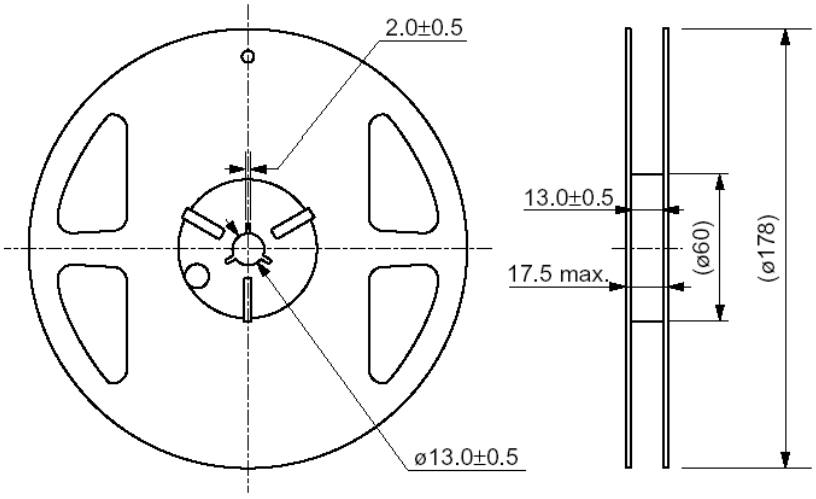
[Figure 1] Carrier Tape Dimensions



[Unit:mm]

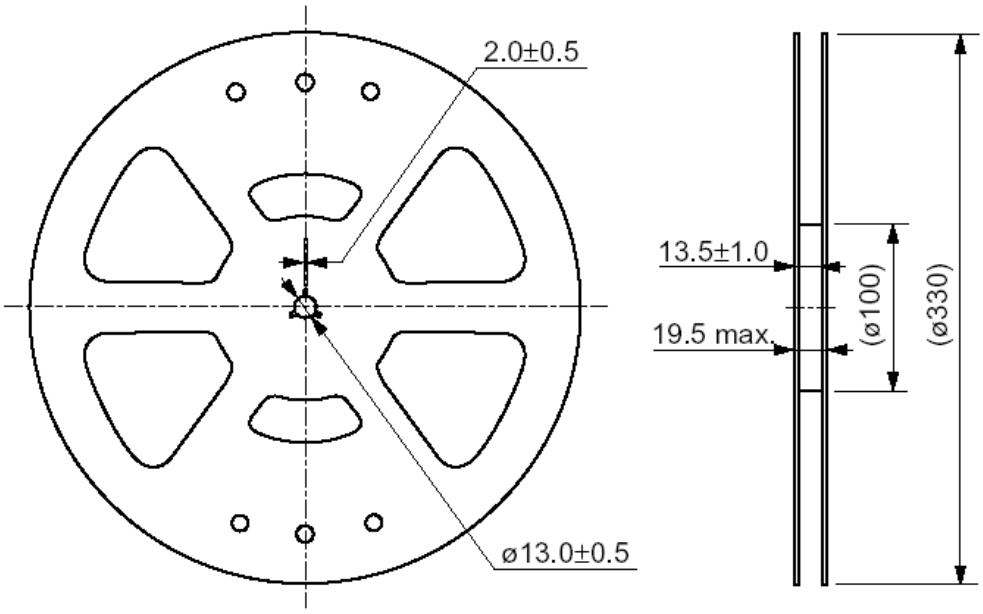
W	F	E	P0	P1	P2	D0	D1	t1	t2	A	B
12.0 ± 0.3	5.5 ± 0.05	1.75 ± 0.1	4.0 ± 0.1	4.0 ± 0.1	2.0 ±0.05	Ø1.5 ±0.1	Ø1.0 ± 0.25	0.3 ± 0.05	1.25 ± 0.1	3.3± 0.1	3.3 ± 0.1

[Figure 2]



ø178 Reel Dimension

(in mm)



ø330 Reel Dimension

(in mm)